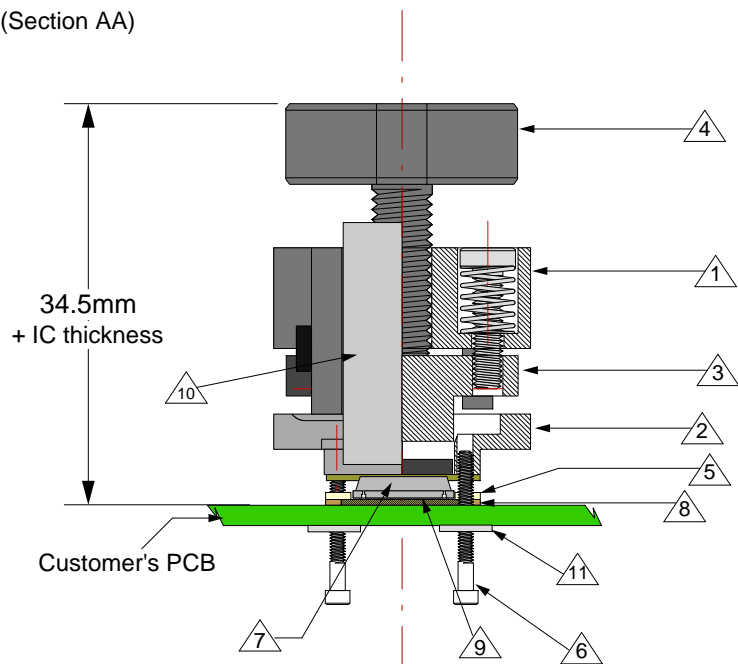


Side View  
(Section AA)




### Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

### Materials:

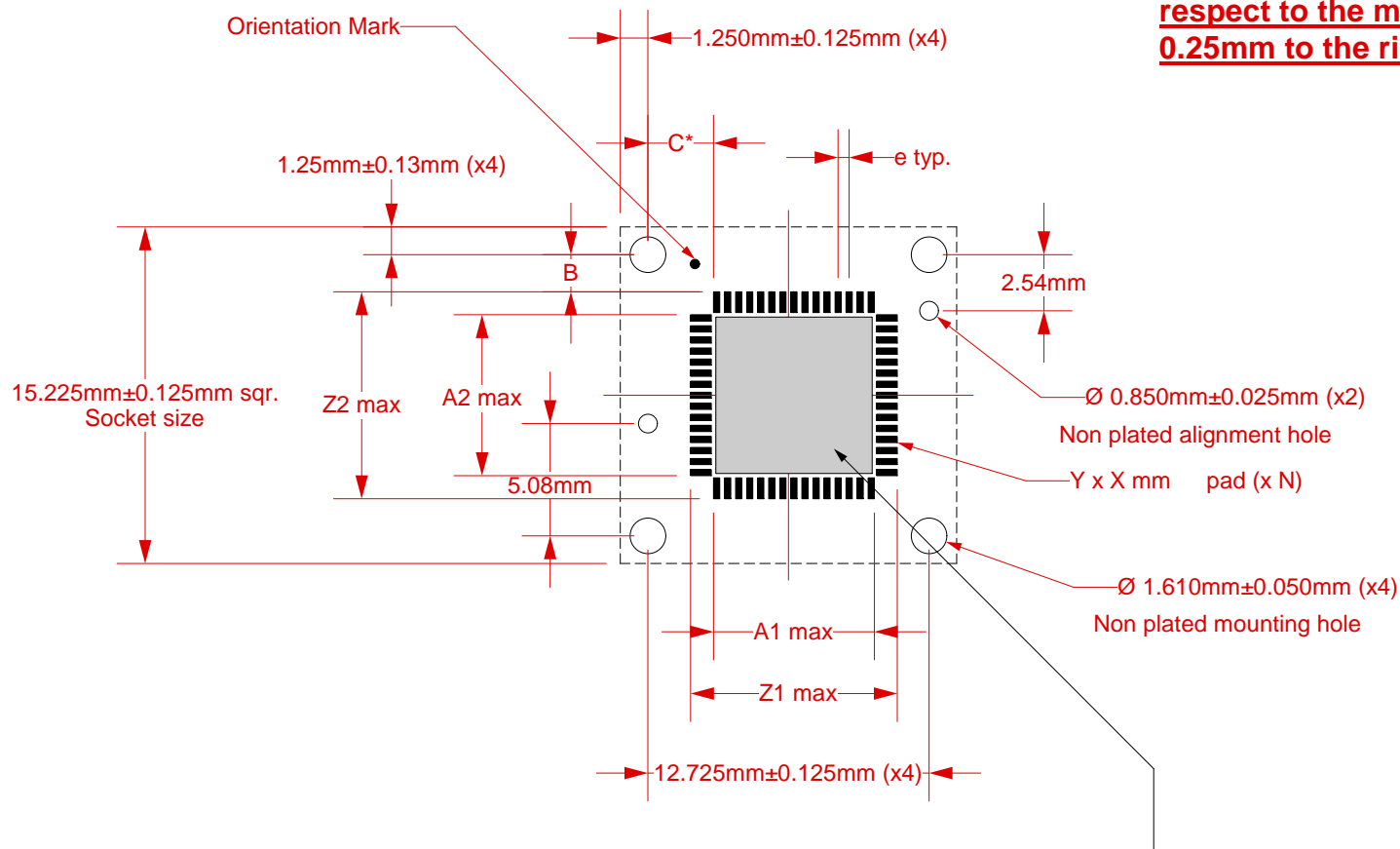
- 1 Clam Shell Lid: Black anodized Aluminum.  
Height = 16.5 mm.
- 2 Socket Base: Black anodized Aluminum.  
Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum.  
Thickness = 8.5 mm.
- 4 Compression Screw: Clear anodized Aluminum.  
Height = 25 mm, Fluted Knob
- 5 IC Guide: Torlon
- 6 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 3/8" long.
- 7 Customer's QFN IC
- 8 Elastomer Guide: Non-clad FR4.  
Thickness = 0.475mm.
- 9 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 10 Latch: Black anodised Aluminum.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD  
0.64mm thickness.

	<b>CG-QFN-7003 Drawing</b>	Status: Released	Scale: -	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: M.A. Fedde		Date: 11/2/09
		File: CG-QFN-7003 Dwg.mcd	Modified: 05/06/14, DH	

All Tolerances:  $\pm 0.125$ mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout  
Top View

**\*Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**




\*\*\*\* To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.

Target PCB Recommendations

Total thickness: 1.6mm min.  
 Plating: Gold or Solder finish  
 PCB Pad height: Same or higher than solder mask

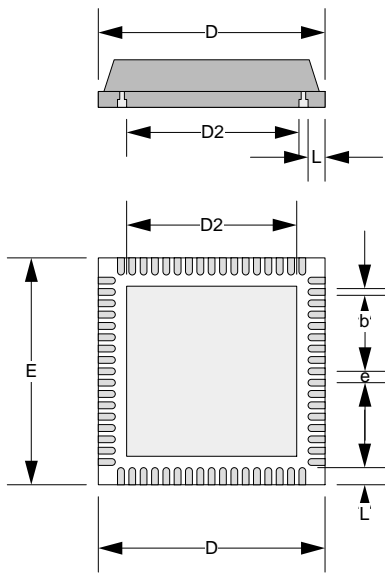
	<b>CG-QFN-7003 Drawing</b>	Status: Released	Scale: 3:1	Rev: B
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		File: CG-QFN-7003 Dwg.mcd	Modified: 05/06/14, DH	

Recommended PCB Layout  
 Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ]  
 unless stated otherwise.


Package Code	C	B	Z1max	A1max	Z2max	A2 max	e	Xmax	Yref	N	Thermal Pad Recommendations
MLF44A	2.4	1.18	10.36	8.42	10.36	8.42	0.8	0.44	1.06	44	7.84 x 7.84
MLF52A	2.53	1.18	10.36	8.17	10.36	8.17	0.65	0.37	1	52	6.84 x 6.84
MLF64B	2.72	1.18	10.36	7.78	10.36	7.78	0.5	0.28	0.94	64	8.08 x 8.08
MLF68A	2.47	1.18	10.36	8.28	10.36	8.28	0.5	0.28	0.94	68	8.08 x 8.08
MLF72A	2.22	1.18	10.36	8.78	10.36	8.78	0.5	0.28	0.69	72	8.58 x 8.58
MLF84A	2.49	1.18	10.36	8.25	10.36	8.25	0.4	0.25	0.81	84	8.34 x 8.34
MLF88A	2.29	1.18	10.36	8.65	10.36	8.65	0.4	0.25	0.76	88	8.2 x 8.2

Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  unless stated otherwise.

All dimensions are in mm.



Package Code	e	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
MLF44A	0.8	9.85	10.15	9.85	10.15	0.28	0.4	0.5	0.75	7.94	44
MLF52A	0.65	9.85	10.15	9.85	10.15	0.23	0.35	0.5	0.75	8.07	52
MLF64B	0.5	9.85	10.15	9.85	10.15	0.21	0.25	0.45	0.55	7.05	64
MLF68A	0.5	9.85	10.15	9.85	10.15	0.18	0.3	0.5	0.75	8.18	68
MLF72A	0.5	9.85	10.15	9.85	10.15	0.18	0.3	0.3	0.5	8.68	72
MLF84A	0.4	9.85	10.15	9.85	10.15	0.16	0.27	0.3	0.5	8.44	84
MLF88A	0.4	9.85	10.15	9.85	10.15	0.15	0.25	0.35	0.45	8.2	88

CG-QFN-7003 Drawing		Status: Released	Scale: -	Rev: B
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